
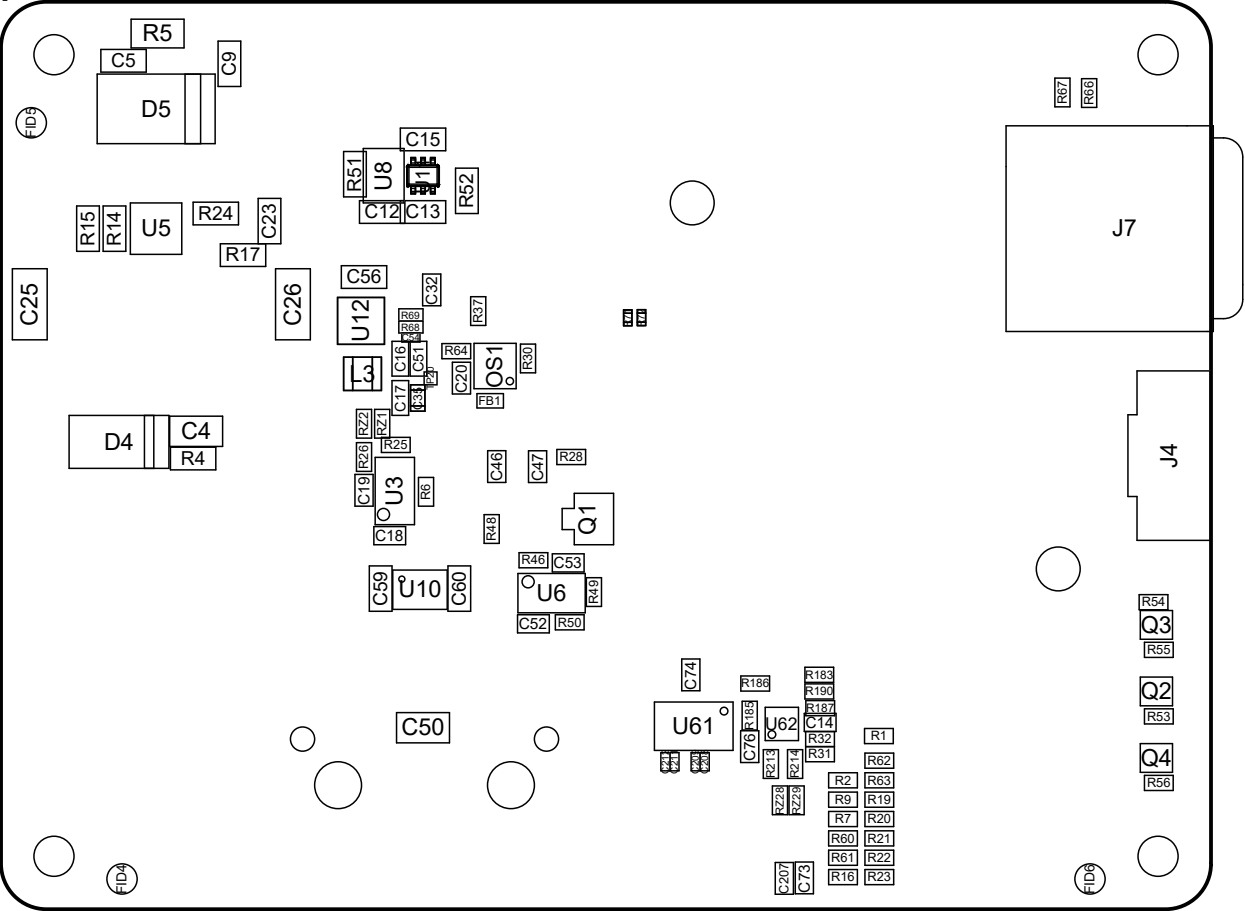


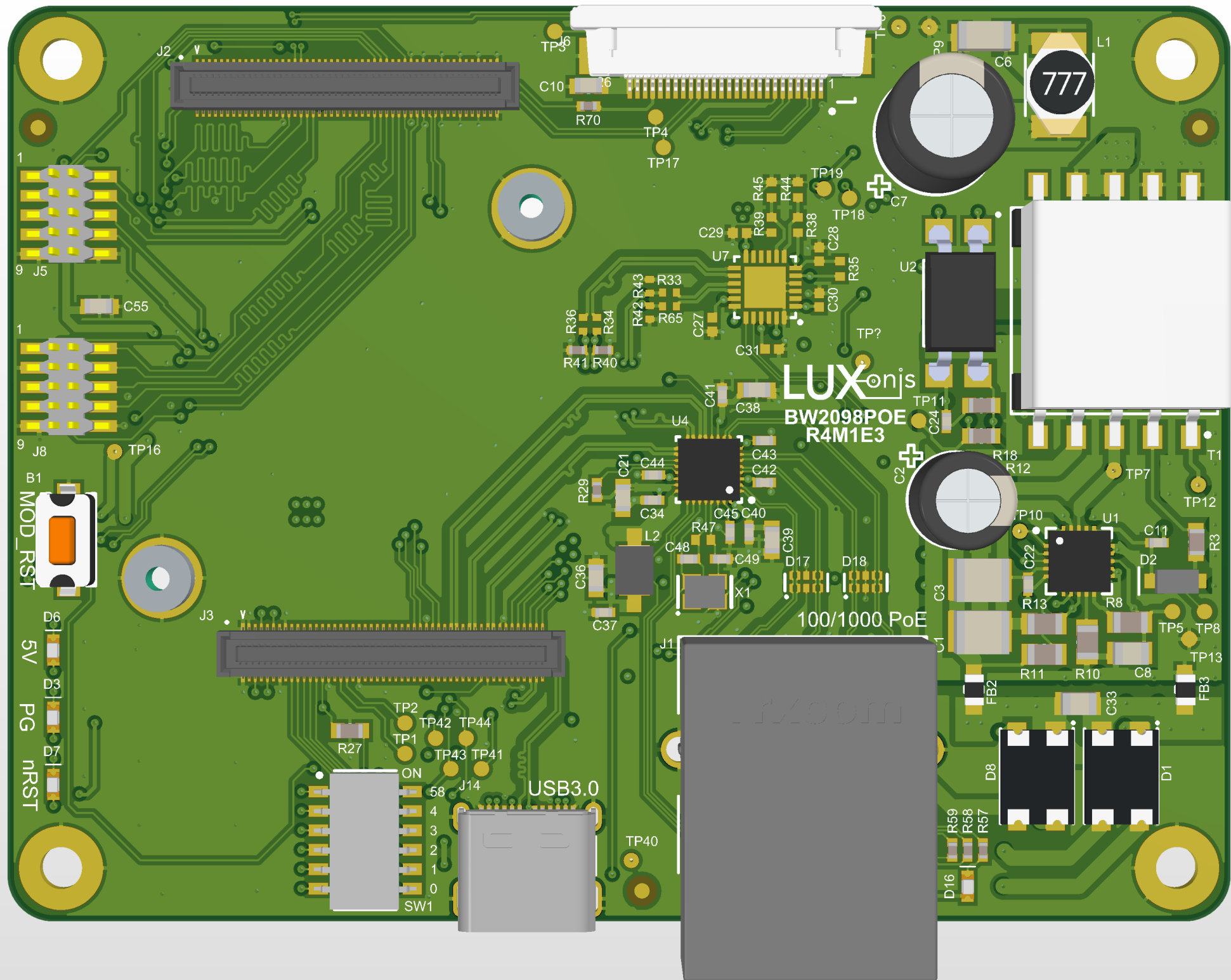
Assembly shall conform to IPC-A-610 Class 2.
Assembly shall conform with RoHS Directive 2011/65/EU.
Components shall be placed according to the associated CPL and BOM documents.
Lead-free SAC305 solder shall be used.
Reflow profile shall comply with J-STD-20C Lead-Free Reflow Profile.
BGA components shall be 100% checked with x-ray for solder bridges after reflow.
Finished assemblies shall be removed from panel prior to delivery.

Title: BW2098POE		
Number: D2098000	Revision: R4M1 E3	
Date: 22/05/2024	Sheet: 1 of 2	PROPRIETARY AND CONFIDENTIAL
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[Variant:]: View from Bottom side (Scale 2:1)



Title: BW2098POE		
Number: D2098000	Revision: R4M1 E3	
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LUXonjs

BW2098POE
R4M1E3

J5 Header

MOD_nRST	I2C3_SCL
AUX_IO_IRQ	I2C3_SDA
2485_PGOOD	UART_RX
NC	UART_TX
GND	GND

J8 Header

SPI_SCK	SPI_SIO0
GND	SPI_SIO1
SPI_SS_0	SPI_SIO2
GPIO6	SPI_SIO3
GND	GND

SDIO

MODULE_JTAG

R54
Q3
R55
Q2
R53
Q4
R56

U61
C74
R186
R185
C76
R213
C208
C209
C211
C212
R183
U62
R190
R187
C14
R32
R31
R2
R214
R9
R7
R60
R61
C207
C73
R16
R1
R62
R63
R19
R20
R21
R22
R23

C15
U8
R51
C12
C13
R52
U11
C56
C32
C33
R37
R64
OS1
R30
R72
R71
C20
FB1
C46
R28
C47
C1
R48
R46
C53
U6
R49
C52
R50
C18
U10
C39
C60
C26
C25
C4
R4
R15
R14
R17
R24
C23
U5
D5
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